MAX-M8

u-blox M8 concurrent GNSS modules

Hardware Integration Manual

Abstract

This document describes the features and specifications of the cost effective and high-performance MAX-M8 modules, which feature the u-blox M8 concurrent GNSS engine with reception of GPS, GLONASS, BeiDou and QZSS signals.

www.u-blox.com

UBX-13004876 - R09

Document Information

Title	MAX-M8
Subtitle	u-blox M8 concurrent GNSS modules
Document type	Hardware Integration Manual
Document number	UBX-13004876
Revision and Date	R09 16-Nov-2015
Document status	Production Information

Document status explanation	
Objective Specification	Document contains target values. Revised and supplementary data will be published later.
Advance Information	Document contains data based on early testing. Revised and supplementary data will be published later.
Early Production Information	Document contains data from product verification. Revised and supplementary data may be published later.
Production Information	Document contains the final product specification.

This document applies to the following products:

Product name	Type number	ROM/FLASH version	PCN reference
MAX-M8C	MAX-M8C-0-02	ROM 2.01	UBX-15015253
MAX-M8W	MAX-M8W-0-00	ROM 2.01	N/A
MAX-M8Q	MAX-M8Q-0-01	ROM 2.01	UBX-15015253

Contents

1 Hardware description

1.1 Overview

u-blox M8 modules are standalone GNSS positioning modules featuring the high performance u-blox M8 positioning engine. Available in industry standard form factors in leadless chip carrier (LCC) packages, they are easy to integrate and combine exceptional positioning performance with highly flexible power, design, and connectivity options. SMT pads allow fully automated assembly with standard pick & place and reflow-soldering equipment for cost-efficient, high-volume production enabling short time-to-market.

☞ For product features see the *MAX-M8 Data Sheet* [1].

☞ To determine which u-blox product best meets your needs, see the product selector tables on the u-blox website www.u-blox.com.

1.2 Configuration

The configuration settings can be modified using UBX protocol configuration messages; see the *u-blox M8 Receiver Description Including Protocol Specification* [2]. The modified settings remain effective until power-down or reset. If these settings have been stored in BBR (Battery Backed RAM), then the modified configuration will be retained, as long as the backup battery supply is not interrupted.

Electrical Programmable Fuse (eFuse)

u-blox M8 modules include an integrated eFuse memory for permanently saving configuration settings.

⚠ **eFuse is One-Time-Programmable; it cannot be changed if it has been programmed once.**

In order to save backup current, a u-blox MAX-M8C module configured in "single crystal" mode can have the single-crystal feature turned off by means of a SW command. Hot start performance will be degraded (no time information at startup).

Use the string in Table 1 to turn-off the single-crystal feature. This is recommended for low power applications, especially if time will be delivered by GSM or uC.

eFuse	String
turn-off single-crystal feature	B5 62 06 41 09 00 01 01 92 81 E6 39 93 2B EE 30 31

Table 1: String to turn off single-crystal feature

1.3 Connecting power

u-blox MAX-M8 positioning modules have up to three power supply pins: **VCC**, **VCC_IO**, and **V_BCKP**.

VCC: Main supply voltage

The **VCC** pin provides the main supply voltage. During operation, the current drawn by the module can vary by some orders of magnitude, especially if enabling low-power operation modes. For this reason, it is important that the supply circuitry be able to support the peak power for a short time (see the *MAX-M8 Data Sheet* [1] for specification).

☞ When switching from backup mode to normal operation or at start-up, u-blox M8 modules must charge the internal capacitors in the core domain. In certain situations, this can result in a significant current draw. For low-power applications using Power Save and backup modes it is important that the power supply or low ESR capacitors at the module input can deliver this current/charge.

☞ Use a proper GND concept. Do not use any resistors or coils in the power line.

VCC_IO: IO Supply Voltage

VCC_IO from the host system supplies the digital I/Os. The wide range of VCC_IO allows seamless interfacing to standard logic voltage levels independent of the VCC voltage level. In many applications, VCC_IO is simply connected to the main supply voltage.

☞ Without a VCC_IO supply, the system will remain in reset state.

V_BCKP: Backup supply voltage

If there is a power failure on the module supply, the real-time clock (RTC) and battery backed RAM (BBR) are supplied through the **V_BCKP** pin. Use of valid time and the GNSS orbit data at start up will improve the GNSS performance, as with hot and warm starts. If no backup battery is connected, the module performs a cold start at power up.

☞ Avoid high resistance on the **V_BCKP** line: During the switch from main supply to backup supply, a short current adjustment peak can cause high voltage drop on the pin with possible malfunctions.

☞ If no backup supply voltage is available, connect the **V_BCKP** pin to **VCC**.

☞ As long as power is supplied to the u-blox M8 module through the **VCC** pin, the backup battery is disconnected from the RTC and the BBR to avoid unnecessary battery drain (see Figure 1). In this case, **VCC** supplies power to the RTC and BBR.
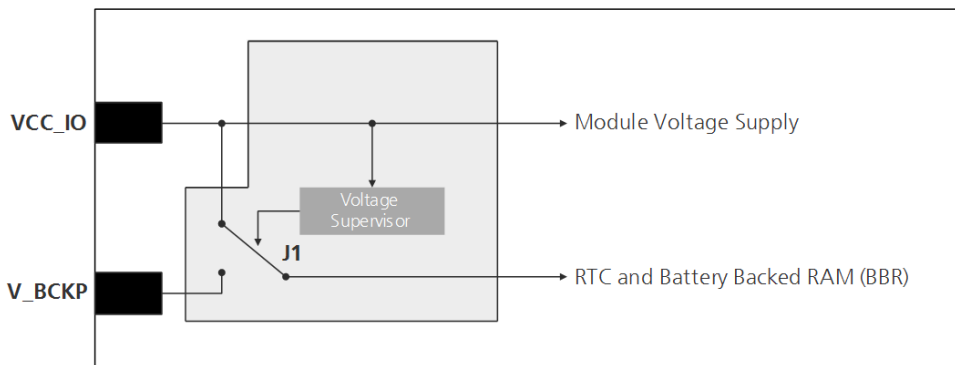
Figure 1: Backup battery and voltage (for exact pin orientation, see the *MAX-M8 Data Sheet* [1])

RTC derived from the system clock; "Single Crystal" feature (MAX-M8C)

On MAX-M8C, the reference frequency for the RTC clock will be internally derived from the crystal system clock frequency (26 MHz) when in Hardware Backup Mode. This feature is called "single crystal" operation. In the event of a power failure, the backup battery at V_BCKP will supply the crystal, as needed to derive and maintain the RTC clock. This makes MAX-M8C a more cost efficient solution at the expense of a higher backup current, as compared to other MAX-M8 variants that use an ordinary RTC crystal. Therefore, the capacity of the backup battery at V_BCKP must be increased if Hardware Backup Mode is needed. (See the *MAX-M8 Data Sheet* [1] for specification.)

In order to save backup current, a u-blox MAX-M8C module configured in "single crystal" mode can have the single-crystal feature turned off by means of a SW command, see section 1.2 and the *u-blox M8 Receiver Description Including Protocol Specification* [2]. Hot start Performance will be degraded (no time information at startup).

VCC_RF: Output voltage RF

The **VCC_RF** pin can supply an active antenna or external LNA. For more information, see section 2.4

V_ANT: Antenna supply (MAX-M8W)

The **V_ANT** pin is available to provide antenna bias voltage to supply an optional external active antenna. For more information, see section 2.5.

☞ If not used, connect the **V_ANT** pin to GND.

1.4 Interfaces

UART

u-blox M8 positioning modules include a Universal Asynchronous Receiver Transmitter (UART) serial interface **RxD/TxD** that supports configurable baud rates. The baud rates supported are specified in the *MAX-M8 Data Sheet* [1]. The signal output and input levels are 0 V to **VCC_IO**. An interface based on RS232 standard levels (+/- 12 V) can be implemented using level shifters such as Maxim MAX3232. Hardware handshake signals and synchronous operation are not supported.

Display Data Channel (DDC)

An I²C compatible Display Data Channel (DDC) interface is available with u-blox M8 modules for serial communication with an external host CPU. The interface only supports operation in slave mode (master mode is not supported). The DDC protocol and electrical interface are fully compatible with the Fast-Mode of the I²C industry standard. DDC pins **SDA** and **SCL** have internal pull-up resistors.

For more information about the DDC implementation, see the *u-blox M8 Receiver Description Including Protocol Specification* [2]. For bandwidth information, see the *MAX-M8 Data Sheet* [1]. For timing, parameters consult the *I²C-bus specification* [5].

☞ The u-blox M8 DDC interface supports serial communication with u-blox cellular modules. See the specification of the applicable cellular module to confirm compatibility.

TX Ready signal

The TX Ready signal indicates that the receiver has data to transmit. A listener can wait on the TX Ready signal instead of polling the DDC or SPI interfaces. The UBX-CFG-PRT message lets you configure the polarity and the number of bytes in the buffer before the TX Ready signal goes active. The TX Ready signal can be mapped to UART TXD (PIO 06). The TX Ready function is disabled by default.

☞ The TX Ready functionality can be enabled and configured by AT commands sent to the u-blox cellular module supporting the feature. For more information see the *GPS Implementation and Aiding Features in u-blox wireless modules* [6].

1.5 I/O pins

RESET_N: Reset input

Driving **RESET_N** low activates a hardware reset of the system. Use this pin only to reset the module. Do not use **RESET_N** to turn the module on and off, since the reset state increases power consumption. In u-blox M8 modules, **RESET_N** is an input only.

☞ No additional capacitance should be added on reset_n pin to GND.

EXTINT: External interrupt

EXTINT is an external interrupt pin with fixed input voltage thresholds with respect to **VCC_IO** (see the *MAX-M8 Data Sheet* [1] for more information). It can be used for wake-up functions in Power Save Mode on all u-blox M8 modules and for aiding. Leave open if unused; the functions are disabled by default.

SAFEBOOT_N

If the SAFEBOOT_N pin is "low" at start up, the u-blox M8 module starts in Safe Boot Mode and doesn't begin GNSS operation. The Safe Boot Mode can be used to recover from situations where the Flash has become corrupted.

ANT_ON: Antenna ON (LNA enable) (MAX-M8Q, MAX-M8C)

In Power Save Mode, the system can turn on/off an optional external LNA using the ANT_ON signal in order to optimize power consumption. A pull-down resistor (10 kΩ) is required to ensure correct operation in backup mode of the ANT_ON signal.

Antenna Short circuit detection (MAX-M8W)

MAX-M8W module includes internal short circuit antenna detection. For more information, see section 2.5.2.

Antenna open circuit detection

Antenna open circuit detection (MAX-M8)

Antenna open circuit detection (OCD) is not activated by default on the MAX-M8 modules. OCD can be mapped to PIO13 (EXTINT). For more information about how to implement OCD, see section 2.5.3. To learn how to configure OCD see the *u-blox M8 Receiver Description Including Protocol Specification* [2].

TIMEPULSE

A configurable time pulse signal is available with all u-blox M8 modules. By default, the time pulse signal is configured to 1 pulse per second. For more information, see the *u-blox M8 Receiver Description Including Protocol Specification* [2].

Electromagnetic interference on I/O lines

Any I/O signal line with a length greater than approximately 3 mm can act as an antenna and may pick up arbitrary RF signals transferring them as noise into the GNSS receiver. This specifically applies to unshielded lines, in which the corresponding GND layer is remote or missing entirely, and lines close to the edges of the printed circuit board.

If, for example, a cellular signal radiates into an unshielded high-impedance line, it is possible to generate noise in the order of volts and not only distort receiver operation but also damage it permanently.

On the other hand, noise generated at the I/O pins will emit from unshielded I/O lines. Receiver performance may be degraded when this noise is coupled into the GNSS antenna (see Figure 20).

To avoid interference by improperly shielded lines, it is recommended to use resistors (e.g. R>20 Ω), ferrite beads (e.g. BLM15HD102SN1) or inductors (e.g. LQG15HS47NJ02) on the I/O lines in series. These components should be chosen with care because they will affect also the signal rise times.

Figure 2 shows an example of EMI protection measures on the RX/TX line using a ferrite bead. More information can be found in section 4.3.
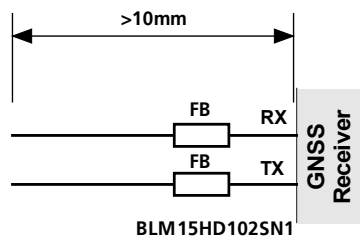

Figure 2: EMI Precautions

2 Design

2.1 Pin description

Function	PIN	No	I/O	Description	Remarks
Power	**VCC**	8	I	Supply Voltage	Provide clean and stable supply.
	GND	1,10,12	I	Ground	Assure a good **GND** connection to all **GND** pins of the module, preferably with a large ground plane.
	V_BCKP	6	I	Backup Supply Voltage	Backup supply voltage input pin. Connect to **VCC_IO** if not used.
Antenna	**RF_IN**	11	I	GNSS signal input from antenna	The connection to the antenna has to be routed on the PCB. Use a controlled impedance of 50 Ω to connect RF_IN to the antenna or the antenna connector. DC block inside.
	VCC_RF	14	O	Output Voltage RF section	Can be used for active antenna or external LNA supply.
	ANT_ON (MAX-M8C/Q)	13	O	ANT_ON	Active antenna or ext. LNA control pin in power save mode. ANT_ON pin voltage level is VCC_IO
	Reserved (MAX-M8W)		-	Reserved	Leave open
UART	**TXD**	2	O	Serial Port	UART, leave open if not used, Voltage level referred VCC_IO. Can be configured as TX Ready indication for the DDC interface.
	RXD	3	I	Serial Port	UART, leave open if not used, Voltage level referred VCC_IO
System	**TIMEPULSE**	4	O	Timepulse Signal	Leave open if not used, Voltage level referred VCC_IO
	EXTINT (AADET_N)	5	I	External Interrupt	Leave open if not used, Voltage level referred VCC_IO
	SDA	16	I/O	DDC Pins	DDC Data. Leave open, if not used.
	SCL	17	I	DDC Pins	DDC Clock. Leave open, if not used.
	VCC_IO	7	I	VCC_IO	IO supply voltage. Input must be always supplied. Usually connect to VCC Pin 8
	RESET_N	9	I	Reset	Reset
	V_ANT (MAX-M8W)	15	I	Antenna Bias Voltage	Connect to **GND** (or leave open) if passive antenna is used. If an active antenna is used, add a 10 Ω resistor in front of **V_ANT** input to the Antenna Bias Voltage or **VCC_RF**
	Reserved (MAX-M8C/Q)		-	Reserved	Leave open
	SAFEBOOT_N	18	I	SAFEBOOT_N	For future service, updates and reconfiguration, leave OPEN

Table 2: Pinout MAX-M8

2.2 Minimal design

This is a minimal setup for a MAX-M8 GNSS receiver:
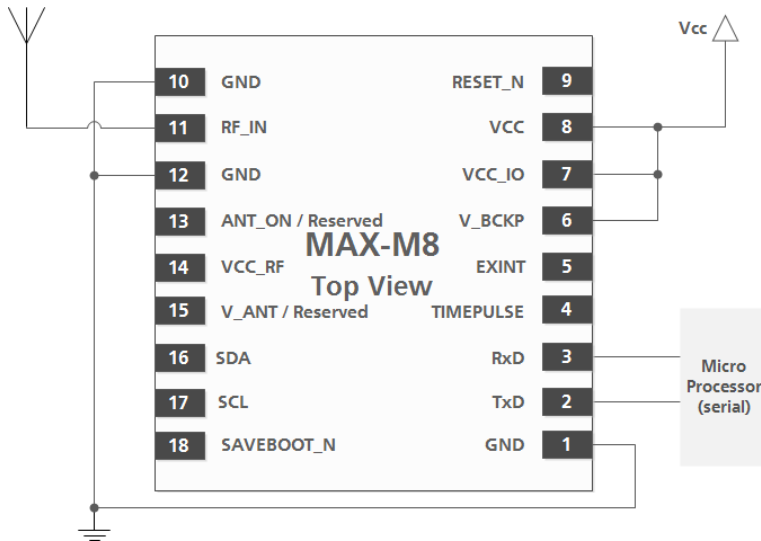

Figure 3: MAX-M8 passive antenna design

☞ For information on increasing immunity to jammers such as GSM, see section 4.3.

2.3 Layout: Footprint and paste mask

Figure 4 describes the footprint and provides recommendations for the paste mask for MAX-M8 LCC modules. These are recommendations only, and not specifications. Note that the copper and solder masks have the same size and position.

To improve the wetting of the half vias, reduce the amount of solder paste under the module and increase the volume outside of the module by defining the dimensions of the paste mask to form a T-shape (or equivalent) extending beyond the copper mask. For the stencil thickness, see section 4.2.

☞ Consider the paste mask outline when defining the minimal distance to the next component. The exact geometry, distances, stencil thicknesses and solder paste volumes must be adapted to the specific production processes (e.g. soldering) of the customer.
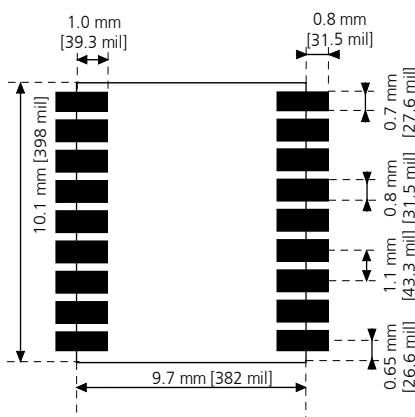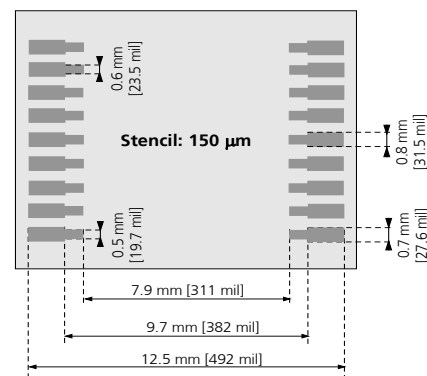

Figure 4: MAX-M8 footprint

Figure 5: MAX-M8 paste mask

☞ MAX Form Factor (10.1 x 9.7 x 2.5): Same Pitch as NEO for all pins: 1.1 mm, but 4 pads in each corner (pin 1, 9, 10 and 18) only 0.7 mm wide instead 0.8 mm

2.4 Antenna and Antenna supervision

Antenna design with passive antenna

A design using a passive antenna requires more attention to the layout of the RF section. Typically, a passive antenna is located near electronic components; therefore, care should be taken to reduce electrical noise that may interfere with the antenna performance. Passive antennas do not require a DC bias voltage and can be directly connected to the RF input pin **RF_IN**. Sometimes they may also need a passive matching network to match the impedance to 50 Ω.

Figure 6 shows a minimal setup for a design with a good GNSS patch antenna.
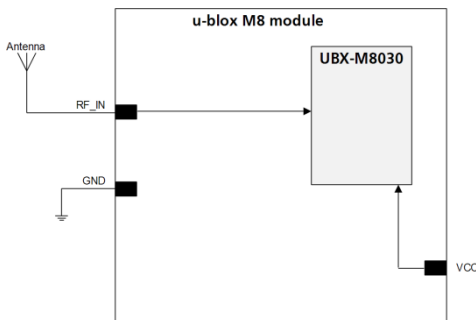
Figure 6: Module design with passive antenna (for exact pin orientation see the *MAX-M8 Data Sheet* [1])

☞ Use an antenna that has sufficient bandwidth to receive all GNSS constellations. See Appendix.

Figure 7 shows a design using an external LNA to increase the sensitivity for best performance with passive antenna.
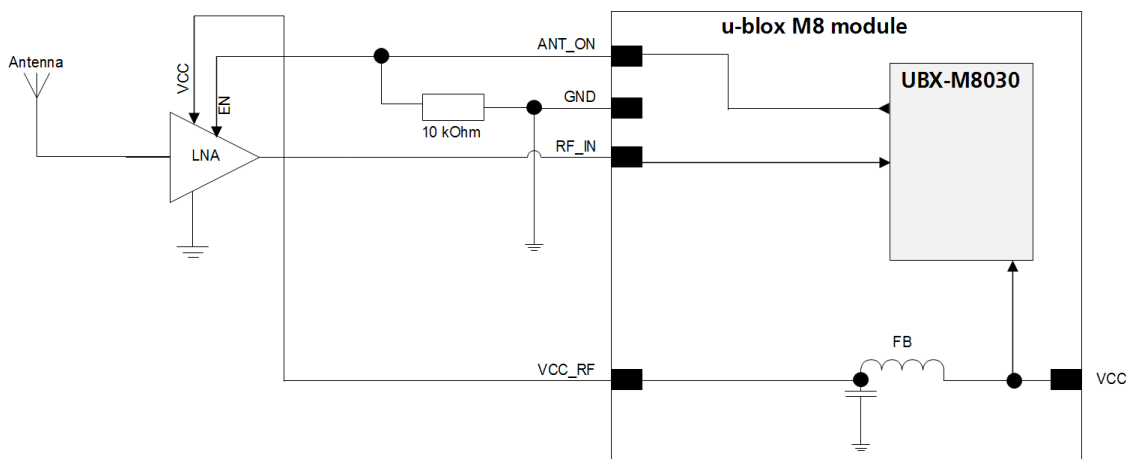
Figure 7: Module design with passive antenna and an external LNA (for exact pin orientation see the *MAX-M8 Data Sheet* [1])

The **ANT_ON** pin (antenna on) can be used to turn on and off an optional external LNA in power save mode in on/off operation.

The **VCC_RF** output can be used to supply the LNA with a filtered supply voltage.

☞ A standard GNSS LNA has enough bandwidth to amplify GPS/GLONASS/BeiDou signals.

☞ An external LNA is only required if the antenna is far away. In that case, the LNA has to be placed close to the passive antenna.

Active antenna design

Active antennas have an integrated low-noise amplifier. Active antennas require a power supply that will contribute to the total GNSS system power consumption budget with additional 5 to 20 mA typically.

If the supply voltage of the MAX-M8 receiver matches the supply voltage of the antenna (e.g. 3.0 V), use the filtered supply voltage available at pin **VCC_RF** as shown in Figure 8.

Active antenna design using VCC_RF pin to supply the active antenna
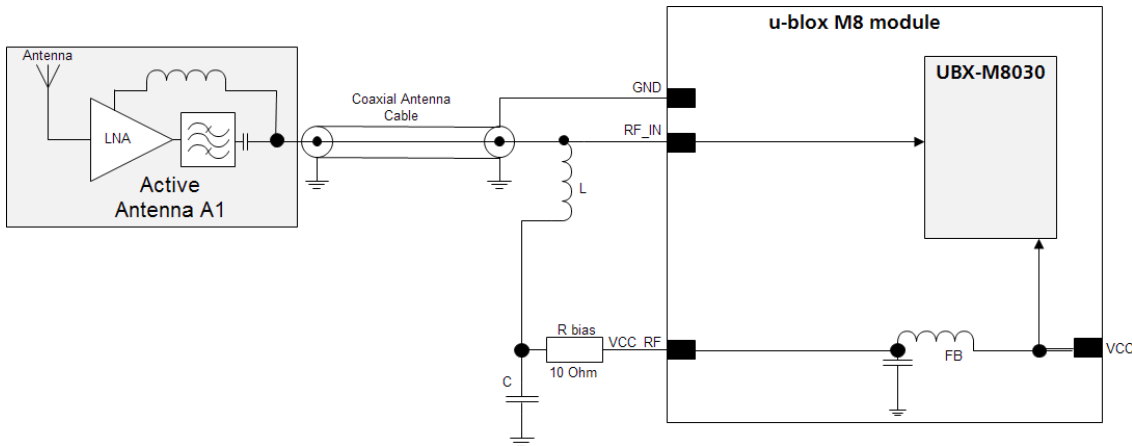
Figure 8: Active antenna design, external supply from VCC_RF (for exact pin orientation see the *MAX-M8 Data Sheet* [1])

In case the **VCC_RF** voltage does not match with the supply voltage of the active antenna, use a filtered external supply as shown in Figure 9.

Active antenna design powered from external supply
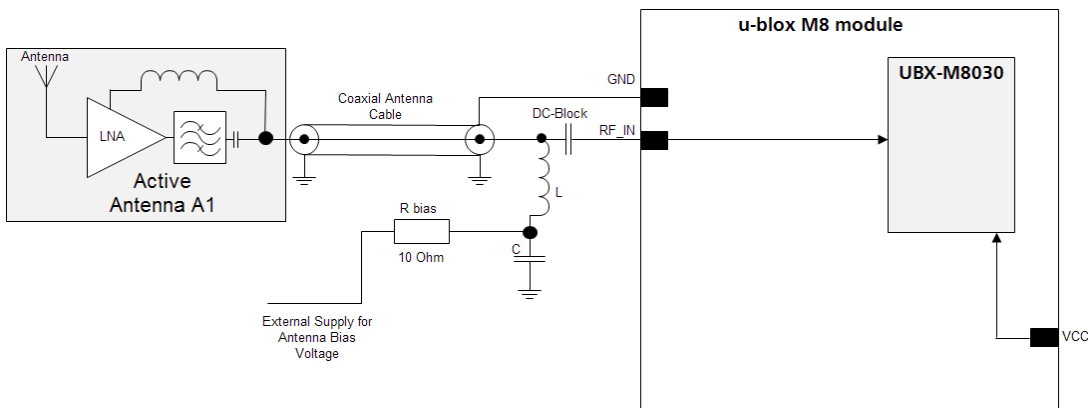
Figure 9: Active antenna design, direct external supply (for exact pin orientation see the *MAX-M8 Data Sheet* [1])

☞ The circuit shown in Figure 9 works with all u-blox M8 modules, also with modules without **VCC_RF** output.

2.5 Antenna design with active antenna using antenna supervisor (MAX-M8W)

An active antenna supervisor provides the means to check the antenna for open and short circuits and to shut off the antenna supply if a short circuit is detected. The Antenna Supervisor is configured using serial port UBX binary protocol message. Once enabled, the active antenna supervisor produces status messages, reporting in

NMEA and/or UBX binary protocol (see section 2.5.1). These indicate the particular state of the antenna supervisor shown in the state diagram below (Figure 10).

The current active antenna status can be determined by polling the UBX-MON-HW monitor command. If an antenna is connected, the initial state after power-up is "Active Antenna OK."
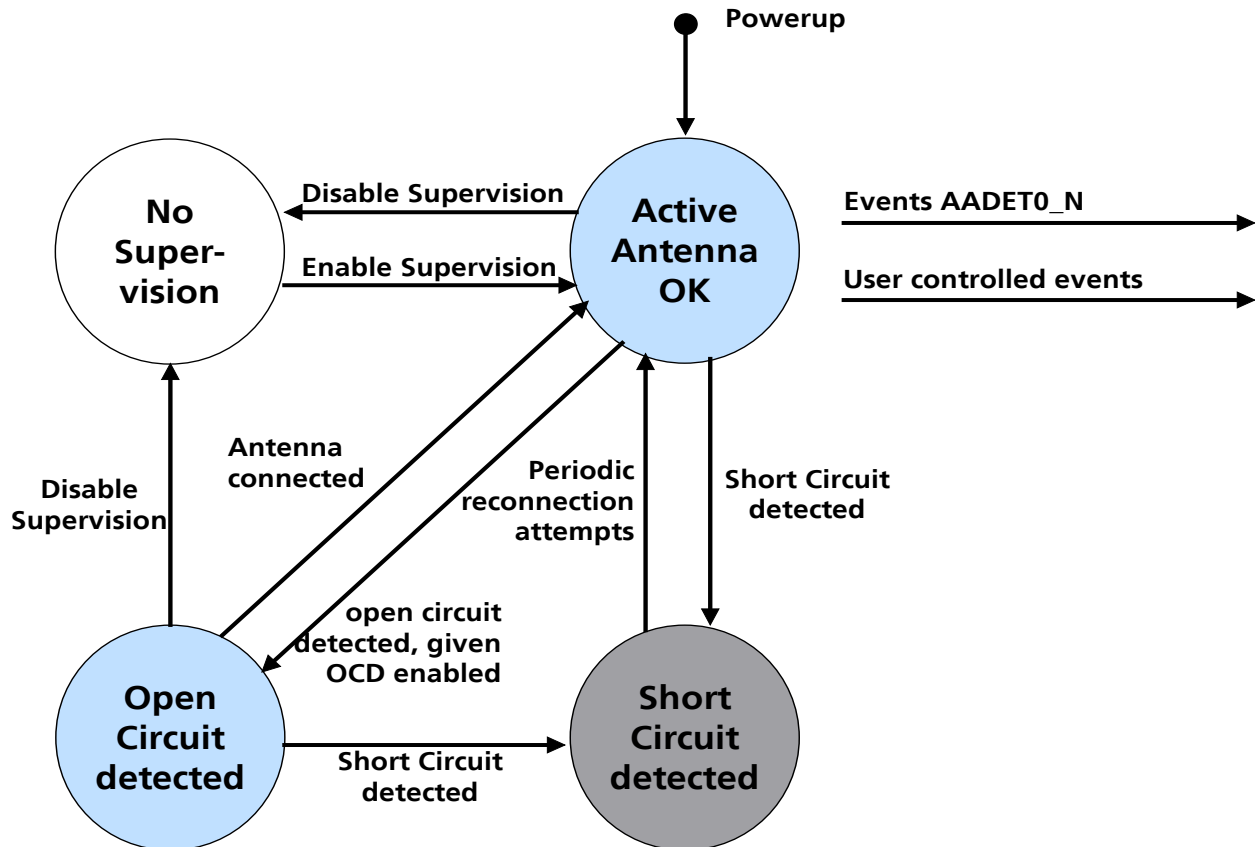
Figure 10: State diagram of active antenna supervisor

The module firmware supports an active antenna supervisor circuit, which is connected to the pin EXTINT. For an example of an open circuit detection circuit, see Figure 13. High on EXTINT means that an external antenna is not connected.

☞ Antenna open circuit detection (OCD) is not activated by default on the MAX-M8 modules. OCD can be mapped to PIO13 (EXTINT). To activate the antenna supervisor use the UBX-CFG-ANT message. For more information about how to implement and configure OCD, see the *u-blox M8 Receiver Description Including Protocol Specification* [2].

☞ For recommended parts for the designs that follow, see the Appendix.

2.5.1 Status reporting

At startup and on every change of the antenna supervisor configuration the u-blox MAX-M8 modules will output an NMEA (**$GPTXT**) or UBX (**INF-NOTICE**) message with the internal status of the antenna supervisor (disabled, short detection only, enabled).

Abbreviation	Description
AC	Antenna Control (e.g. the antenna will be switched on/ off controlled by the GPS receiver)
SD	Short Circuit Detection Enabled
SR	Short Circuit Recovery Enabled
OD	Open Circuit Detection Enabled
PdoS	Power Down on short

Table 3: Active Antenna Supervisor Message on startup (UBX binary protocol)

☞ To activate the antenna supervisor use the UBX-CFG-ANT message. For further information refer to the *u-blox M8 Receiver Description Including Protocol Specification* [2].

Similar to the antenna supervisor configuration, the status of the antenna supervisor will be reported in an NMEA (**$GPTXT**) or UBX (**INF-NOTICE**) message at start-up and on every change.

Message	Description
ANTSTATUS=DONTKNOW	Active antenna supervisor is not configured and deactivated.
ANTSTATUS=OK	Active antenna connected and powered
ANTSTATUS=SHORT	Antenna short
ANTSTATUS=OPEN	Antenna not connected or antenna defective

Table 4: Active antenna supervisor message on startup (NMEA protocol)

2.5.2 Module design with active antenna, short circuit protection/detection (MAX-M8W)

If a suitably dimensioned series resistor **R_BIAS** is placed in front of pin **V_ANT**, a short circuit can be detected in the antenna supply. This is detected inside the u-blox M8 module and the antenna supply voltage will be immediately shut down. After which, periodic attempts to re-establish antenna power are made by default.

An internal switch (under control of the receiver) can turn off the supply to the external antenna whenever it is not needed. This feature helps to reduce power consumption in power save mode.

☞ To configure the antenna supervisor use the UBX-CFG-ANT message. For further information see *u-blox M8 Receiver Description Including Protocol Specification* [2].

☞ Short circuits on the antenna input without limitation (R_BIAS) of the current can result in permanent damage to the receiver! Therefore, it is mandatory to implement an R_BIAS in all risk applications, such as situations where the antenna can be disconnected by the end-user or that have long antenna cables.

☞ In case VCC_RF voltage does not match with the antenna supply voltage, use a filtered external supply as shown in Figure 12.

Supply from VCC_RF (MAX-M8W)

Figure 11 shows an active antenna supplied from the u-blox MAX-M8W module.

The **VCC_RF** pin can be connected with **V_ANT** to supply the antenna. Note that the voltage specification of the antenna has to match the actual supply voltage of the u-blox module (e.g. 3.0 V), see Figure 11.

Figure 11: Module design with active antenna, internal supply from VCC_RF (for exact pin orientation, see the *MAX-M8 Data Sheet* [1])

External supply (MAX-M8W)

Figure 12 shows an externally powered active antenna design.

Since the external bias voltage is fed into the most sensitive part of the receiver (i.e. the RF input), this supply should be free of noise. Usually, low frequency analog noise is less critical than digital noise of spurious frequencies with harmonics up to the GNSS frequency. Therefore, it is not recommended to use digital supply nets to feed the **V_ANT** pin.

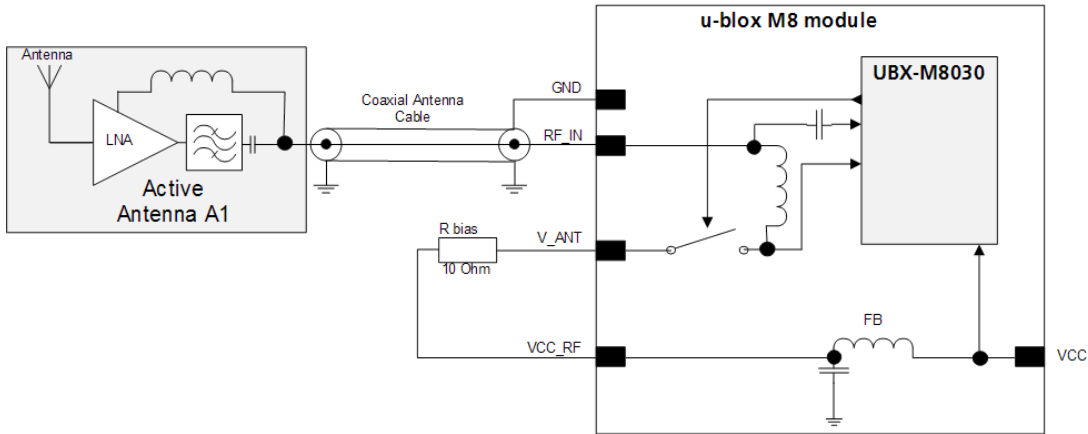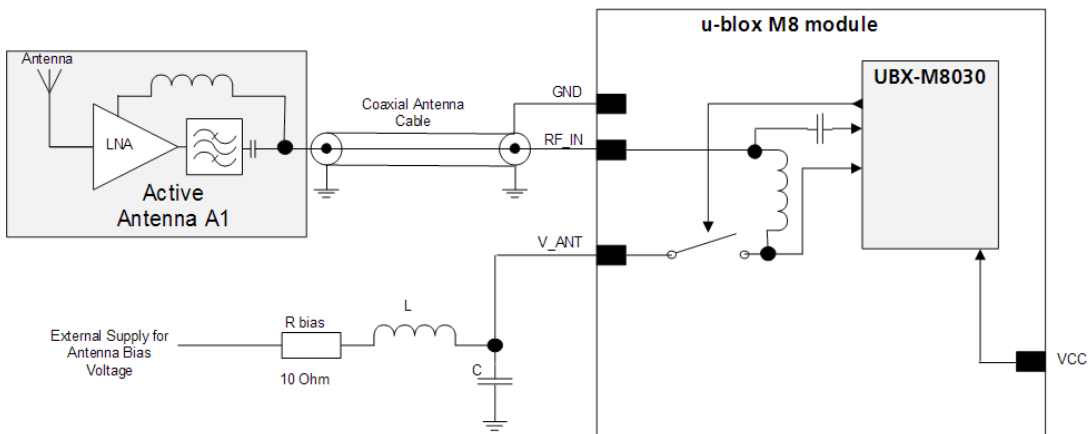**Figure 12: Module design with active antenna, external supply (for exact pin orientation, see the *MAX-M8 Data Sheet* [1])**

2.5.3 Antenna supervision open circuit detection (OCD) (MAX-M8W)

The open circuit detection circuit uses the current flow to detect an open circuit in the antenna. Calculate the threshold current using Equation 1.
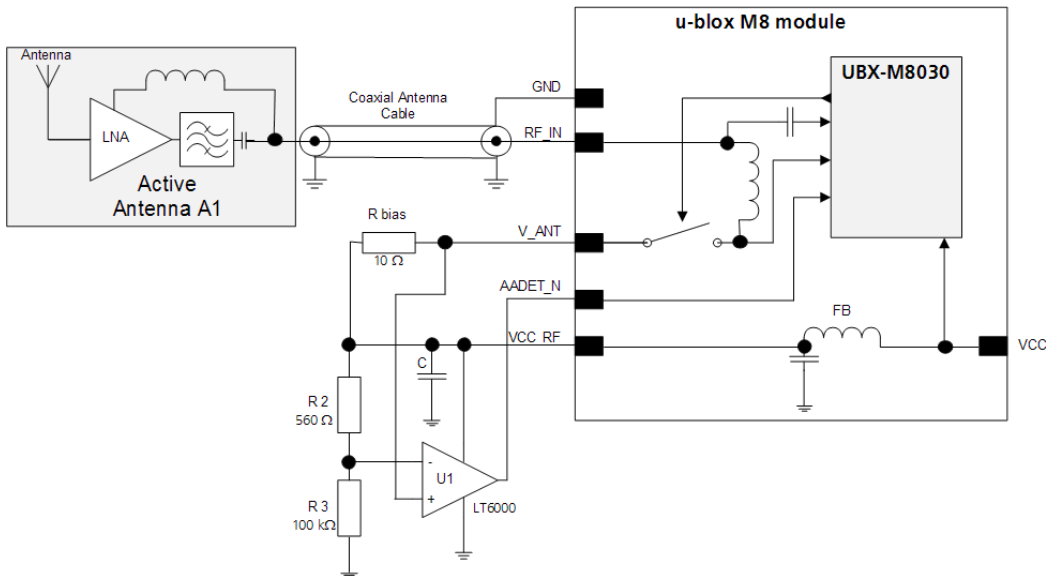
Figure 13: Schematic of open circuit detection (for exact pin orientation, see data sheet)

$$I = \frac{\left(\dfrac{R2}{R2+R3}\right)}{Rbias} \bullet Vcc\_RF$$

Equation 1: Calculation of threshold current for open circuit detection

☞ Antenna open circuit detection (OCD) is not activated by default. It can be enabled by the UBX-CFG-ANT message. This configuration must be sent to the receiver at every.

MAX-M8W does not have a dedicated AADET_N pin. The AADET_N pin can be made available on the EXINT pin. To do so, the following command must be sent once and stored permanently to the receiver:
"B5 62 06 41 0C 00 00 00 03 1F 06 5F 8B B1 FF F6 B7 FF C1 D7".

To enable the OCD feature, the following command must be sent to the receiver at every startup:
"B5 62 06 13 04 00 1F 00 F0 B5 E1 DE".

The AADET_N pin then has High = "ANTSTATUS=OPEN", Low = "ANTSTATUS=OK".

For more information about how to implement and configure OCD, see the *u-blox M8 Receiver Description Including Protocol Specification* [2].

☞ If the antenna supply voltage is not derived from VCC_RF, do not exceed the maximum voltage rating of AADET_N.

2.5.4 External active antenna supervisor using customer uP (MAX-M8Q, MAX-M8C)
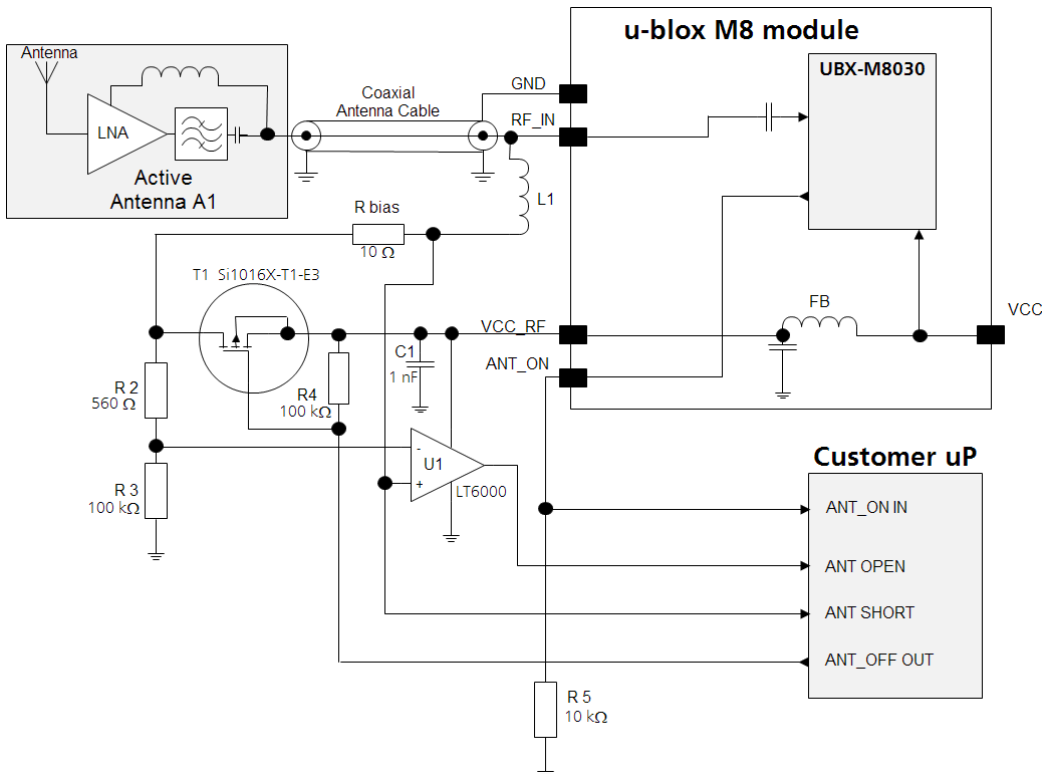
Figure 14: External active antenna supervisor using ANT_ON

$$I = \frac{\left(\dfrac{R2}{R2+R3}\right)}{R_{bias}} \bullet Vcc\_RF$$

Equation 2: Calculation of threshold current for open circuit detection

2.5.5 External active antenna control (MAX-M8Q, MAX-M8C)

The ANT_ON signal can be used to turn on and off an external LNA. This reduces power consumption in Power Save Mode (Backup mode).
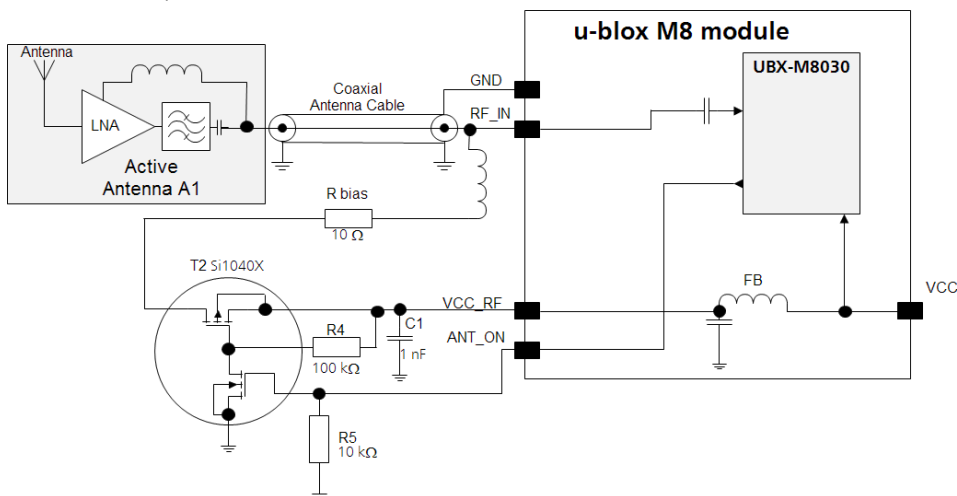
Figure 15: External active antenna control (MAX-M8Q / MAX-M8C)

3 Migration to u-blox M8 modules

3.1 Migrating u-blox 7 designs to a u-blox M8 module

u-blox is committed to ensuring that products in the same form factor are backwards compatible over several technology generations. Utmost care has been taken to ensure there is no negative impact on function or performance and to make u-blox M8 modules as fully compatible as possible with u-blox 7 versions. No limitations of the standard features have resulted. If using BeiDou, check the bandwidth of the external RF components and the antenna. For power consumption information, see the *MAX-M8 Data Sheet* [1].

It is highly advisable that customers consider a design review with the u-blox support team to ensure the compatibility of key functionalities.

3.2 Hardware migration from MAX-6 to MAX-M8

| Pin	MAX-6		MAX-M8		Remarks for Migration
	Pin Name	Typical Assignment	Pin Name	Typical Assignment	
1	GND	GND	GND	GND	No difference
2	TxD	Serial Port	TxD	Serial Port	No difference
3	RxD	Serial Port	RxD	Serial Port	No difference
4	TIMEPULSE	Timepulse (1PPS)	TIMEPULSE	Timepulse (1PPS)	No difference
5	EXTINT0	External Interrupt Pin	EXTINT0	External Interrupt Pin	No difference
6	V_BCKP	Backup Supply Voltage	V_BCKP	Backup Supply Voltage	If this was connected to GND on u-blox 6 module, OK to do the same in u-blox M8. (MAX-M8C: Higher backup current, see 0 Single Crystal)
7	VCC_IO	IO supply voltage Input must always be supplied. Usually connect to VCC Pin 8	VCC_IO	IO supply voltage Input must always be supplied. Usually connect to VCC Pin 8	No difference
8	**VCC**	**Module power supply MAX-6G 1.75 – 2.0V MAX-6Q/C: 2.7 – 3.6V**	**VCC**	**Module power supply MAX-M8C: 1.65 – 3.6V MAX-M8Q: 2.7 – 3.6V**	
9	**VRESET**	**connect to pin 8**	**RESET_N**	**Reset input**	If pin 9 is connected directly to pin 8, the RESET function is not available. If the RESET function shall be used, a 3k3 resistor from pin 9 to pin 8 in conjunction with an open drain buffer is required for u-blox 6. For MAX-M8 modules pin 8 can be connected to pin 9 or can be left open. Do not populate the 3k3 resistor. Behavior of RESET_N has changed; For u-blox 7 and M8, a RESET will erase the time information in the BBR, which was maintained in u-blox 6. Therefore, with u-blox 7 and M8 a RESET will not result in a hot start, etc.
10	GND	GND	GND	GND	No difference
11	RF_IN	Matched RF-Input, DC block inside.	RF_IN	Matched RF-Input, DC block inside.	No difference
12	GND	GND	GND	GND	No difference
13	ANT_ON	Active antenna or ext. LNA control pin in power save mode. **ANT_ON pin voltage level: MAX-6 -> VCC_RF (pull-up)**	ANT_ON	Active antenna or ext. LNA control pin in power save mode. **ANT_ON pin voltage level: MAX-M8 -> VCC_IO (push-pull)**	**On MAX-6, ANT_ON pin voltage level is with respect to VCC_RF, on MAX-M8 to VCC_IO** (only relevant when VCC_IO does not share the same supply with VCC)
14	VCC_RF	Can be used for active antenna or external LNA supply.	VCC_RF	Can be used for active antenna or external LNA supply.	No difference
15	RESERVED	Leave open.	RESERVED (**MAX-M8W:**	Leave open.	No difference

Pin	MAX-6		MAX-M8		Remarks for Migration
	Pin Name	Typical Assignment	Pin Name	Typical Assignment	
			V_ANT)		
16	SDA	DDC Data	SDA	DDC Data	No difference
17	SCL	DDC Clock	SCL	DDC Clock	No difference
18	SAFEBOOT_N	Leave open.	SAFEBOOT_N	Leave open.	No difference

Table 5: Pin-out comparison MAX-6 vs. MAX-M8

3.3 Software migration

☞ For an overall description of the module software operation, see the *u-blox M8 Receiver Description Including Protocol Specification* [2].

☞ For migration, see *u-blox 7 to u-blox M8 Software Migration Guide* [7].

4 Product handling

4.1 Packaging, shipping, storage and moisture preconditioning

For information pertaining to reels and tapes, Moisture Sensitivity levels (MSL), shipment and storage information, as well as drying for preconditioning, see the *MAX-M8 Data Sheet* [1].

Population of Modules

☞   When populating the modules make sure that the pick and place machine is aligned to the copper pins of the module and not on the module edge.

4.2 Soldering

Soldering paste

Use of "No Clean" soldering paste is strongly recommended, as it does not require cleaning after the soldering process has taken place. The paste listed in the example below meets these criteria.

Soldering Paste: OM338 SAC405 / Nr.143714 (Cookson Electronics)

Alloy specification: Sn 95.5/ Ag 4/ Cu 0.5 (95.5% Tin/ 4% Silver/ 0.5% Copper)

Melting Temperature: 217° C

Stencil Thickness: See section 2.3

The final choice of the soldering paste depends on the approved manufacturing procedures.

The paste-mask geometry for applying soldering paste should meet the recommendations.

☞   The quality of the solder joints on the connectors ("half vias") should meet the appropriate IPC specification.

Reflow soldering

A convection type-soldering oven is highly recommended over the infrared type radiation oven. Convection heated ovens allow precise control of the temperature and all parts will be heated up evenly, regardless of material properties, thickness of components and surface color.

Consider the IPC-7530 Guidelines for temperature profiling for mass soldering (reflow and wave) processes, published 2001.

Preheat phase

Initial heating of component leads and balls. Residual humidity will be dried out. Note that this preheat phase will not replace prior baking procedures.

- Temperature rise rate: max. 3° C/s. If the temperature rise is too rapid in the preheat phase it may cause excessive slumping.
- Time: 60 – 120 s. If the preheat is insufficient, rather large solder balls tend to be generated. Conversely, if performed excessively, fine balls and large balls will be generated in clusters.
- End Temperature: 150 – 200° C. If the temperature is too low, non-melting tends to be caused in areas containing large heat capacity.

Heating/ Reflow phase

The temperature rises above the liquidus temperature of 217° C. Avoid a sudden rise in temperature as the slump of the paste could become worse.

- Limit time above 217° C liquidus temperature: 40 – 60 s
- Peak reflow temperature: 245° C

Cooling phase

A controlled cooling avoids negative metallurgical effects (solder becomes more brittle) of the solder and possible mechanical tensions in the products. Controlled cooling helps to achieve bright solder fillets with a good shape and low contact angle.

- Temperature fall rate: max 4° C/s

☞ To avoid falling off, the u-blox M8 GNSS module should be placed on the topside of the motherboard during soldering.

The final soldering temperature chosen at the factory depends on additional external factors like choice of soldering paste, size, thickness and properties of the baseboard, etc. Exceeding the maximum soldering temperature in the recommended soldering profile may permanently damage the module.
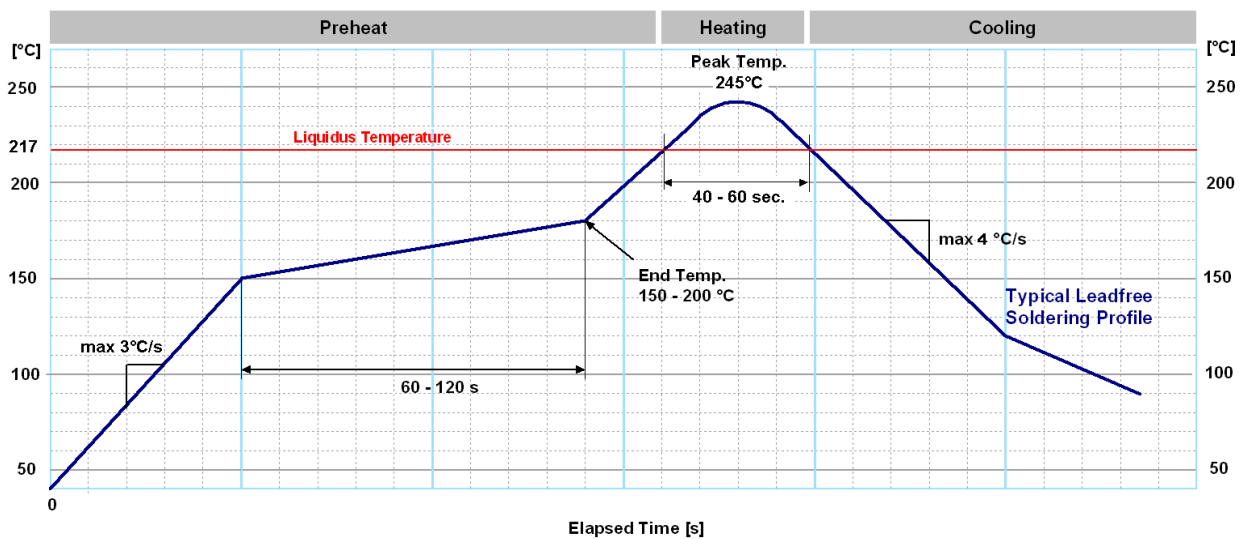

Figure 16: Recommended soldering profile

☞ u-blox M8 modules **must not** be soldered with a damp heat process.

Optical inspection

After soldering the u-blox M8 module, consider an optical inspection step to check whether:

- The module is properly aligned and centered over the pads
- All pads are properly soldered
- No excess solder has created contacts to neighboring pads, or possibly to pad stacks and vias nearby

Cleaning

In general, cleaning the populated modules is strongly discouraged. Residues underneath the modules cannot be easily removed with a washing process.

- Cleaning with water will lead to capillary effects where water is absorbed in the gap between the baseboard and the module. The combination of residues of soldering flux and encapsulated water leads to short circuits or resistor-like interconnections between neighboring pads.
- Cleaning with alcohol or other organic solvents can result in soldering flux residues flooding into the two housings, areas that are not accessible for post-wash inspections. The solvent will also damage the sticker and the ink-jet printed text.
- Ultrasonic cleaning will permanently damage the module, in particular the quartz oscillators.

The best approach is to use a "no clean" soldering paste and eliminate the cleaning step after the soldering.

Repeated reflow soldering

Only single reflow soldering processes are recommended for boards populated with u-blox M8 modules. u-blox M8 modules should not be submitted to two reflow cycles on a board populated with components on both sides in order to avoid upside down orientation during the second reflow cycle. In this case, the module should always be placed on that side of the board, which is submitted into the last reflow cycle. The reason for this (besides others) is the risk of the module falling off due to the significantly higher weight in relation to other components.

Two reflow cycles can be considered by excluding the above described upside down scenario and taking into account the rework conditions described in section Product handling.

☞   Repeated reflow soldering processes and soldering the module upside down are not recommended.

Wave soldering

Base boards with combined through-hole technology (THT) components and surface-mount technology (SMT) devices require wave soldering to solder the THT components. Only a single wave soldering process is encouraged for boards populated with u-blox M8 modules.

Hand soldering

Hand soldering is allowed. Use a soldering iron temperature setting equivalent to 350° C. Place the module precisely on the pads. Start with a cross-diagonal fixture soldering (e.g. pins 1 and 15), and then continue from left to right.

Rework

The u-blox M8 module can be unsoldered from the baseboard using a hot air gun. When using a hot air gun for unsoldering the module, a maximum of one reflow cycle is allowed. In general, we do not recommend using a hot air gun because this is an uncontrolled process and might damage the module.

⚠   **Attention: use of a hot air gun can lead to overheating and severely damage the module. Always avoid overheating the module.**

After the module is removed, clean the pads before placing and hand soldering a new module.

⚠   **Never attempt a rework on the module itself, e.g. replacing individual components. Such actions immediately terminate the warranty.**

In addition to the two reflow cycles, manual rework on particular pins by using a soldering iron is allowed. Manual rework steps on the module can be done several times.

Conformal coating

Certain applications employ a conformal coating of the PCB using HumiSeal® or other related coating products. These materials affect the HF properties of the GNSS module and it is important to prevent them from flowing into the module. The RF shields do not provide 100% protection for the module from coating liquids with low viscosity; therefore, care is required in applying the coating.

☞   Conformal Coating of the module will void the warranty.

Casting

If casting is required, use viscose or another type of silicon pottant. The OEM is strongly advised to qualify such processes in combination with the u-blox M8 module before implementing this in the production.

☞   Casting will void the warranty.

Grounding metal covers

Attempts to improve grounding by soldering ground cables, wick or other forms of metal strips directly onto the EMI covers is done at the customer's own risk. The numerous ground pins should be sufficient to provide optimum immunity to interferences and noise.

☞ u-blox makes no warranty for damages to the u-blox M8 module caused by soldering metal cables or any other forms of metal strips directly onto the EMI covers.

Use of ultrasonic processes

Some components on the u-blox M8 module are sensitive to Ultrasonic Waves. Use of any Ultrasonic Processes (cleaning, welding etc.) may cause damage to the GNSS Receiver.

☞ u-blox offers no warranty against damages to the u-blox M8 module caused by any Ultrasonic Processes.

4.3 EOS/ESD/EMI precautions

When integrating GNSS positioning modules into wireless systems, careful consideration must be given to electromagnetic and voltage susceptibility issues. Wireless systems include components, which can produce Electrical Overstress (EOS) and Electro-Magnetic Interference (EMI). CMOS devices are more sensitive to such influences because their failure mechanism is defined by the applied voltage, whereas bipolar semiconductors are more susceptible to thermal overstress. The following design guidelines are provided to help in designing robust yet cost effective solutions.

⚠ **To avoid overstress damage during production or in the field it is essential to observe strict EOS/ESD/EMI handling and protection measures.**

⚠ **To prevent overstress damage at the RF_IN of your receiver, never exceed the maximum input power (see the *MAX-M8 Data Sheet* [1]).**

Electrostatic discharge (ESD)

Electrostatic discharge (ESD) is the sudden and momentary electric current that flows between two objects at different electrical potentials caused by direct contact or induced by an electrostatic field. The term is usually used in the electronics and other industries to describe momentary unwanted currents that may cause damage to electronic equipment.
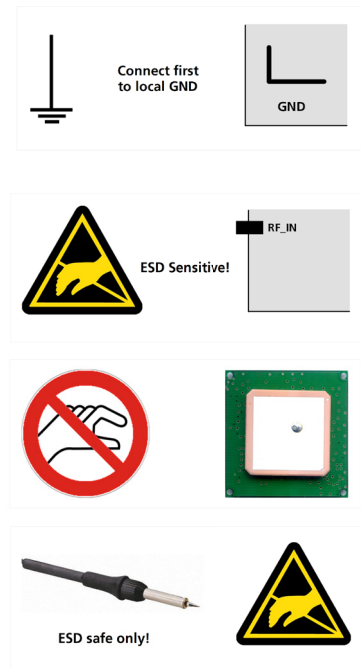
ESD handling precautions

ESD prevention is based on establishing an Electrostatic Protective Area (EPA). The EPA can be a small working station or a large manufacturing area. The main principle of an EPA is that there are no highly charging materials near ESD sensitive electronics, all conductive materials are grounded, workers are grounded, and charge build-up on ESD sensitive electronics is prevented. International standards are used to define typical EPA and can be obtained for example from International Electrotechnical Commission (IEC) or American National Standards Institute (ANSI).

GNSS positioning modules are sensitive to ESD and require special precautions when handling. Particular care must be exercised when handling patch antennas, due to the risk of electrostatic charges. In addition to standard ESD safety practices, the following measures should be taken into account whenever handling the receiver.

- Unless there is a galvanic coupling between the local GND (i.e. the work table) and the PCB GND, then the first point of contact when handling the PCB must always be between the local GND and PCB GND.

- Before mounting an antenna patch, connect ground of the device

- When handling the RF pin, do not come into contact with any charged capacitors and be careful when contacting materials that can develop charges (e.g. patch antenna ~10 pF, coax cable ~50 – 80 pF/m, soldering iron, …)

- To prevent electrostatic discharge through the RF input, do not touch any exposed antenna area. If there is any risk that such exposed antenna area is touched in non ESD protected work area, implement proper ESD protection measures in the design.

- When soldering RF connectors and patch antennas to the receiver's RF pin, make sure to use an ESD safe soldering iron (tip).

⚠️ **Failure to observe these precautions can result in severe damage to the GNSS module!**

ESD protection measures

⚠️ **GNSS positioning modules are sensitive to Electrostatic Discharge (ESD). Special precautions are required when handling.**

☞ For more robust designs, employ additional ESD protection measures. Using an LNA with appropriate ESD rating can provide enhanced GNSS performance with passive antennas and increases ESD protection.

Most defects caused by ESD can be prevented by following strict ESD protection rules for production and handling. When implementing passive antenna patches or external antenna connection points, then additional ESD measures can also avoid failures in the field as shown in Figure 17.

Small passive antennas (<2 dBic and performance critical)	Passive antennas (>2 dBic or performance sufficient)	Active antennas
A LNA with appropriate ESD rating	B	C

Figure 17: ESD Precautions

☞ Protection measure A is preferred because it offers the best GNSS performance and best level of ESD protection.

Electrical Overstress (EOS)

Electrical Overstress (EOS) usually describes situations when the maximum input power exceeds the maximum specified ratings. EOS failure can happen if RF emitters are close to a GNSS receiver or its antenna. EOS causes damage to the chip structures. If the RF_IN is damaged by EOS, it is hard to determine whether the chip structures have been damaged by ESD or EOS.

EOS protection measures

☞ For designs with GNSS positioning modules and cellular (e.g. GSM/GPRS) transceivers in close proximity, ensure sufficient isolation between the cellular and GNSS antennas. If cellular power output causes the specified maximum power input at the GNSS RF_IN to be exceeded, employ EOS protection measures to prevent overstress damage.

For robustness, EOS protection measures as shown in Figure 18 are recommended for designs combining cellular communication transceivers (e.g. GSM, GPRS) and GNSS in the same design or in close proximity.

Small passive antennas (<2 dBic and performance critical)	Passive antennas (>2 dBic or performance sufficient)	Active antennas (without internal filter which need the module antenna supervisor circuits)
D LNA with appropriate ESD rating and maximum input power	E GNSS Band pass Filter: SAW or Ceramic with low insertion loss and appropriate ESD rating	F

Figure 18: EOS and ESD Precautions

Electromagnetic interference (EMI)

Electromagnetic interference (EMI) is the addition or coupling of energy, which causes a spontaneous reset of the GNSS receiver or results in unstable performance. In addition to EMI degradation due to self-jamming (see section 1.5), any electronic device near the GNSS receiver can emit noise that can lead to EMI disturbances or damage.

The following elements are critical regarding EMI:

* Unshielded connectors (e.g. pin rows etc.)
* Weakly shielded lines on PCB (e.g. on top or bottom layer and especially at the border of a PCB)
* Weak GND concept (e.g. small and/or long ground line connections)

EMI protection measures are recommended when RF emitting devices are near the GNSS receiver. To minimize the effect of EMI a robust grounding concept is essential. To achieve electromagnetic robustness follow the standard EMI suppression techniques.

http://www.murata.com/products/emc/knowhow/index.html

http://www.murata.com/products/emc/knowhow/pdf/4to5e.pdf

Improved EMI protection can be achieved by inserting a resistor or better yet a ferrite bead or an inductor (see Table 6) into any unshielded PCB lines connected to the GNSS receiver. Place the resistor as close as possible to the GNSS receiver pin.

Alternatively, feed-thru capacitors with good GND connection can be used to protect e.g. the **VCC** supply pin against EMI. A selection of feed-thru capacitors are listed in Table 6.

4.4 Applications with cellular modules

GSM uses power levels up to 2 W (+33 dBm). Consult the data sheet for the absolute maximum power input at the GNSS receiver.

See the *GPS Implementation and Aiding Features in u-blox wireless modules* [6].

Isolation between GNSS and GSM antenna

In a handheld type design, an isolation of approximately 20 dB can be reached with careful placement of the antennas. If such isolation cannot be achieved, e.g. in the case of an integrated GSM/GNSS antenna, an additional input filter is needed on the GNSS side to block the high energy emitted by the GSM transmitter. Examples of these kinds of filters would be the SAW Filters from Epcos (B9444 or B7839) or Murata.

Increasing interference immunity

Jamming signals come from in-band and out-band frequency sources.

In-band interference

With in-band jamming, the signal frequency is very close to the GNSS constellation frequency used, e.g. GPS frequency of 1575 MHz (see Figure 19). Such interference signals are typically caused by harmonics from displays, micro-controller, bus systems, etc.
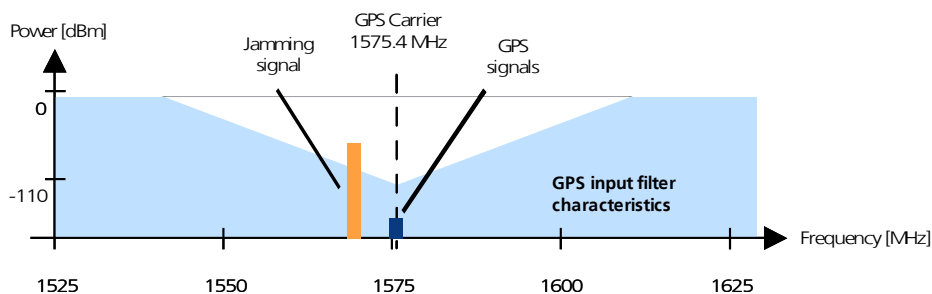
.

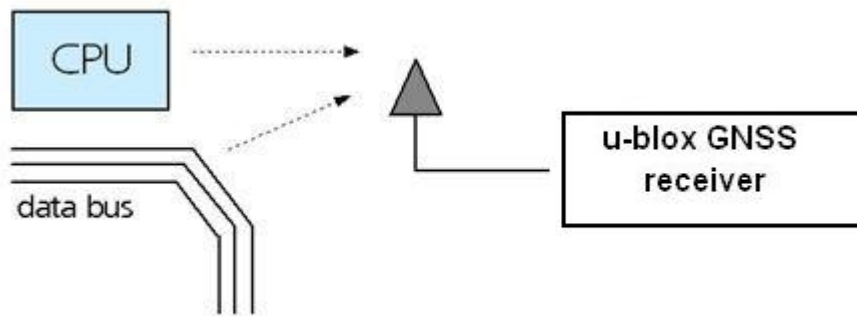**Figure 19: In-band interference signals**

Figure 20: In-band interference sources

Measures against in-band interference include:

- Maintaining a good grounding concept in the design
- Shielding
- Layout optimization
- Filtering
- Placement of the GNSS antenna
- Adding a CDMA, GSM, WCDMA band pass filter before handset antenna

Out-band interference

Out-band interference is caused by signal frequencies that are different from the GNSS carrier (see Figure 21). The main sources are wireless communication systems such as GSM, CDMA, WCDMA, Wi-Fi, BT, etc.
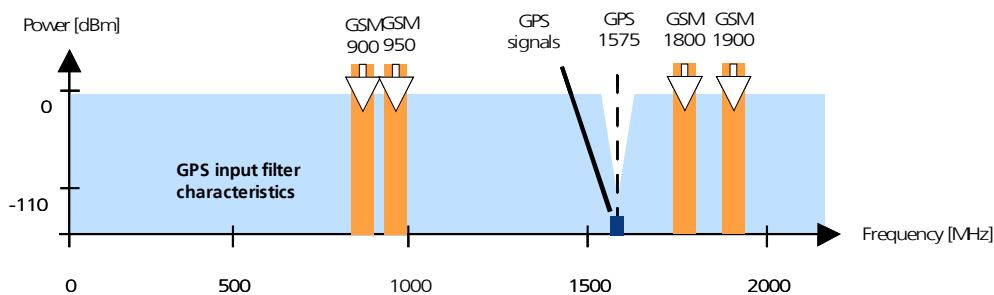
Figure 21: Out-band interference signals

Measures against out-band interference include maintaining a good grounding concept in the design and adding a SAW or band pass ceramic filter (as recommend in Section 4) into the antenna input line to the GNSS receiver (see Figure 22).

Figure 22: Measures against out-band interference

☞ For design-in recommendations in combination to Cellular operation see Appendix

☞ See *the GPS Implementation and Aiding Features in u-blox wireless modules* [6].

Appendix

Recommended parts

Recommended parts are selected on data sheet basis only. Other components may also be used.

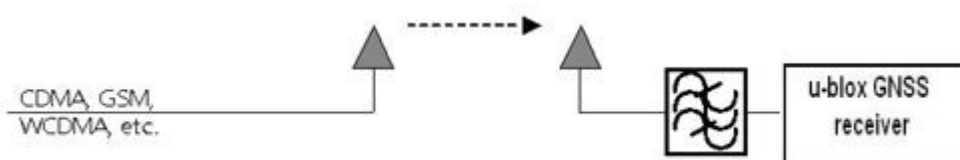| Part	Manufacturer	Part ID	Remarks	Parameters to consider
Diode Semi-conductor	ON	ESD9R3.3ST5G	Standoff Voltage > 3.3 V	Low Capacitance < 0.5 pF
		ESD9L3.3ST5G	Standoff Voltage > 3.3 V	Standoff Voltage > Voltage for active antenna
		ESD9L5.0ST5G	Standoff Voltage > 5 V	Low Inductance
SAW	TDK/ EPCOS	B8401: B39162-B8401-P810	GPS+GLONASS	High attenuation
		B3913: B39162B3913U410	GPS+GLONASS+BeiDou	For automotive application
		B4310: B39162B4310P810	GPS+GLONASS	Compliant to the AEC-Q200 standard
	muRata	SAFFB1G56KB0F0A	GPS+GLONASS+BeiDou	Low insertion loss, only for mobile application
		SAFEA1G58KB0F00	GPS+GLONASS	Low insertion loss, only for mobile application
		SAFEA1G58KA0F00	GPS+GLONASS	High attenuation, only for mobile application
		SAFFB1G58KA0F0A	GPS+GLONASS	High attenuation, only for mobile application
		SAFFB1G58KB0F0A	GPS+GLONASS	Low insertion loss, only for mobile application
	TAI-SAW	TA1573A	GPS+GLONASS	Low insertion loss
		TA0638A	GPS+GLONASS+BeiDou	Low insertion loss
		TA1343A	GPS+GLONASS+BeiDou	Low insertion loss
LNA	JRC	NJG1143UA2	LNA	Low noise figure, up to 15 dBm RF input power
	Avago	ALM-GN001	LNA	Low noise figure, with pre-LNA filter, concurrent GNSS
	Avago	ALM-GN002	LNA	Very low noise figure, with post-LNA filter, concurrent GNSS
Inductor	Murata	LQG15HS27NJ02	L, 27 nH	Impedance @ freq GPS > 500 Ω
Capacitor	Murata	GRM1555C1E470JZ01	C, 47 pF	DC-block
Ferrite Bead	Murata	BLM15HD102SN1	FB	High IZI @ fGSM
Feed thru Capacitor for Signal	Murata	NFL18SP157X1A3	Monolithic Type	For data signals, 34 pF load capacitance
		NFA18SL307V1A45	Array Type	For data signals, 4 circuits in 1 package
Feed thru Capacitor	Murata	NFM18PC ….	0603 2A	Rs < 0.5 Ω
		NFM21P….	0805 4A	
Resistor		10 Ω ± 10%, min 0.250 W	R_{bias}	
		560 Ω ± 5%	R2	
		100 kΩ ± 5%	R3, R4	

Table 6: Recommended parts

Recommended antennas

Manufacturer	Order No.	Comments
Hirschmann (www.hirschmann-car.com)	GLONASS 9 M	GPS+GLONASS active
Taoglas (www.taoglas.com)	AA.160.301111	GPS/GLONASS/BeiDou 36*36*4 mm, 3-5V 30mA active
Taoglas (www.taoglas.com)	AA.161.301111	36*36*3 mm, 1.8 to 5.5V / 10mA at 3V active
INPAQ (www.inpaq.com.tw)	B3G02G-S3-01-A	GPS/GLONASS/BeiDou 2.7 to 3.9 V / 10 mA active
Amotech (www.amotech.co.kr)	B35-3556920-2J2	35x35x3 mm GPS+GLONASS passive
Amotech (www.amotech.co.kr)	A25-4102920-2J3	25x25x4 mm GPS+GLONASS passive
Amotech (www.amotech.co.kr)	A18-4135920-AMT04	18x18x4 mm GPS+GLONASS passive
Amotech (www.amotech.co.kr)	AGA363913-S0-A1	GPS+GLONASS+BeiDou active
INPAQ (www.inpaq.com.tw)	ACM4-5036-A1-CC-S	5.2 x 3.7 x 0.7 mm GPS+GLONASS passive
Additional antenna Manufacturer: Allis Communications, 2J, Tallysman Wireless		

Table 7: Recommend antennas

A.1 Design-in recommendations in combination with cellular operation

Product		Receiver Chain					Cellular and GNSS Simultaneous operation			
							Passive GNSS Antenna		Active GNSS Antenna	
Family	Variant	Antenna	SAW LNA	SAW	On-chip LNA	SAW	2G cellular	3G/4G cellular	2G/3G/4G cellular	
MAX-6	Any				•	•	✓		✓	✓
NEO-6	Any				•	•	✓		✓	✓
LEA-6	Any				•	•	✓		✓	✓
EVA-7	M				•				✓	✓
MAX-7	C				•		✓		✓	✓
	W				•		✓		✓	✓
	Q				•		✓		✓	✓
NEO-7	N		•		•		✓	✓	✓	✓
	M				•		✓		✓	✓
	P			•	•		✓	✓	✓	✓
EVA-M8	M				•				✓	✓
MAX-M8	C				•		✓		✓	✓
	W				•		✓		✓	✓
	Q				•		✓		✓	✓
NEO-M8	N		•		•		✓	✓	✓	✓
	M				•		✓		✓	✓
	Q		•		•		✓	✓	✓	✓
	T		•		•		✓	✓	✓	✓
LEA-M8	S			•	•		✓	✓	✓	✓
	T			•	•		✓	✓	✓	✓
PAM-7	Q	•	•	•	•		✓	✓	✓	✓
CAM-M8	C	•	•		•		✓	✓	✓	✓
	Q	•	•		•		✓	✓	✓	✓

• = integrated   ✓ = optimal performance

Table 8: Combinations of u-blox GNSS modules with different cellular technologies (2G/3G/4G).

☞ See the *GPS Implementation and Aiding Features in u-blox wireless modules* [6].

Related documents

[1]   MAX-M8 Data Sheet, Docu. No. UBX-13004644

[2]   u-blox M8 Receiver Description Including Protocol Specification (Public version), Docu. No. UBX-13003221

[3]   GPS Antenna Application Note, Docu. No. GPS-X-08014

[4]   GPS Compendium, Docu. No. GPS-X-02007

[5]   I^{2}C-bus specification, Version 2.1, Jan 2000,
http://www.nxp.com/acrobat_download/literature/9398/39340011_21.pdf

[6]   GPS Implementation and Aiding Features in u-blox wireless modules, Docu. No. GSM.G1-CS-09007

[7]   u-blox 7 to u-blox M8 Software Migration Guide, Docu. No. UBX-13003254

☞   For regular updates to u-blox documentation and to receive product change notifications, register on our homepage (http://www.u-blox.com)

Revision history

Revision	Date	Name	Status / Comments
R01	30-Jan-2014	jfur	Objective Specification
R02	26-Feb- 2014	jfur	Advance Information
R03	12-May-2014	jfur	Document status changed to Early Production Information. Updated Table 6 (Recommended parts); added Table 8: Combinations of u-blox GNSS modules with different cellular technologies (2G/3G/4G), updated Figure 9, Figure 14 and Figure 15.
R04	02-Jul-2014	jfur	Updated Table 7 (added Amotech GPS+GLONASS+BeiDou active antenna)
R05	19-Sep-2014	jfur	Changed MAX-M8C Type Number to MAX-M8C-0-01, updated SAFEBOOT_N pin description in Table 2, Figure 3 and Table 5.
R06	02-Dec-2014	julu	Production Information. Changed Antenna open circuit detection.
R07	02-Jun-2015	julu	Updated section 1.5 (added Electromagnetic interference on I/O lines), updated Figure 15.
R08	21-Oct-2015	julu	Updated MAX-M8C Type Number to MAX-M8C-0-02 and added relevant PCN reference
R09	16-Nov-2015	julu	Updated MAX-M8Q Type Number to MAX-M8Q-0-01 and added relevant PCN reference

Contact

u-blox Offices

North, Central and South America

u-blox America, Inc.

Phone:	+1 703 483 3180
E-mail:	info_us@u-blox.com

Regional Office West Coast:

Phone:	+1 408 573 3640
E-mail:	info_us@u-blox.com

Technical Support:

Phone:	+1 703 483 3185
E-mail:	support_us@u-blox.com

**Headquarters
Europe, Middle East, Africa**

u-blox AG

Phone:	+41 44 722 74 44
E-mail:	info@u-blox.com
Support:	support@u-blox.com

Asia, Australia, Pacific

u-blox Singapore Pte. Ltd.

Phone:	+65 6734 3811
E-mail:	info_ap@u-blox.com
Support:	support_ap@u-blox.com

Regional Office Australia:

Phone:	+61 2 8448 2016
E-mail:	info_anz@u-blox.com
Support:	support_ap@u-blox.com

Regional Office China (Beijing):

Phone:	+86 10 68 133 545
E-mail:	info_cn@u-blox.com
Support:	support_cn@u-blox.com

Regional Office China (Chongqing):

Phone:	+86 23 6815 1588
E-mail:	info_cn@u-blox.com
Support:	support_cn@u-blox.com

Regional Office China (Shanghai):

Phone:	+86 21 6090 4832
E-mail:	info_cn@u-blox.com
Support:	support_cn@u-blox.com

Regional Office China (Shenzhen):

Phone:	+86 755 8627 1083
E-mail:	info_cn@u-blox.com
Support:	support_cn@u-blox.com

Regional Office India:

Phone:	+91 959 1302 450
E-mail:	info_in@u-blox.com
Support:	support_in@u-blox.com

Regional Office Japan (Osaka):

Phone:	+81 6 6941 3660
E-mail:	info_jp@u-blox.com
Support:	support_jp@u-blox.com

Regional Office Japan (Tokyo):

Phone:	+81 3 5775 3850
E-mail:	info_jp@u-blox.com
Support:	support_jp@u-blox.com

Regional Office Korea:

Phone:	+82 2 542 0861
E-mail:	info_kr@u-blox.com
Support:	support_kr@u-blox.com

Regional Office Taiwan:

Phone:	+886 2 2657 1090
E-mail:	info_tw@u-blox.com
Support:	support_tw@u-blox.com